SP240-Series

SP240 Series is lead-free solder paste designed for stencil printing in surface mount process.

Application

- Available for SMT and die attach process
- Suitable for Dotting, Dispensing, Screen Printing

Features

- This product satisfy Halogen free standard
- Little hardening change in successive printing, and consistent performance for printing
- Excellent wetting performance and minimize of Void
- Little slump after printing so that the reliability of Soldering is high
- No Solder ball issue

Information

Alloy : Sn3.0Ag0.5Cu / Sn0.7Cu (possible to customize)

Particle Size : Type 4 (20~38um),Type 5 (15~25um),Type 6 (5~15um)

Package : 500g , possible to customize

Properties

Spec.	Unit	Value	Measured
Color	-	Gray	Visual
Activity Level	-	ROL0	IPC J-STD-004B
Specific gravity	-	7.4	-
Thixotropic Index (TI)	-	0.4~0.7	MALCOM
Viscosity @ 25°C	Pa.S	LV (40~80) MV (80~140) HV (140~ 230)	MALCOM(10rpm)
Thermal Conductivity	W/mK	63	Laser Flash Diffusivity

• Possible to change for customize (Metal content and viscosity)

Working Time

Spec.	Unit	Value	Measured
Open time	Hour	< 12hrs	-
Work life	Hour	< 8hrs	-
Shelf life	Month	6month	0-10℃

How to Use

1) Thaw

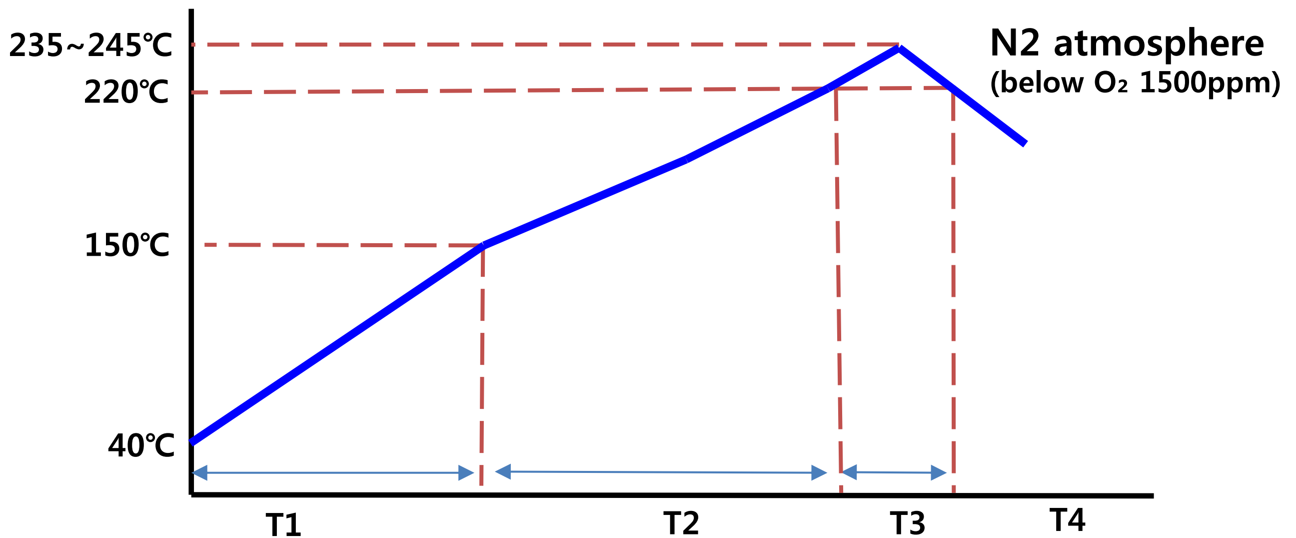
- Allow to reach room temperature before use(2 hours ago) without opening.
  Refrigerated opening can cause solder ball problem.
- Open and use after the paste reach the room temperature(20~25℃).

2) Mix

- Recommend manual mixing(2min ~ 3min)
  Excessive mixing can make the property change.

Spec.	RPM	Sec.
Auto Mixing(Jar)	500	15~20

Reflow Profile



Zone	T1	T2	T3	T4	Peak Temp.
Type	Raising	Preheat 1	Soldering	Cooling	240+/-3℃
Temp(℃)	40~150	150~220	220℃ Above	220℃ Below	
Time(sec)	1~2℃/sec	60~120	40~90	2℃/sec	